



浙江世菱半导体有限公司
ZHEJIANG SHILING SEMICONDUCTOR CO.,LTD.

产品规格书

Specification of products

产品名称：肖特基二极管

产品型号：MBK400U1K2

浙江世菱半导体有限公司
ZHEJIANG SHILING SEMICONDUCTOR CO., LTD.

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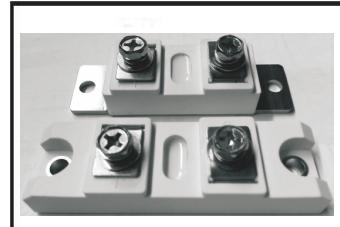
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拟制	审核	核准
林益龙	曹剑龙	宗瑞

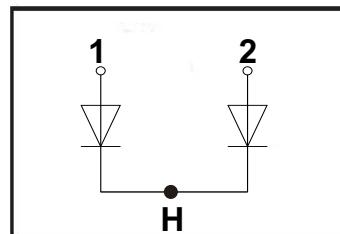
PRODUCT FEATURES

- Ultrafast Reverse Recovery Time
- Soft Reverse Recovery Characteristics
- Low Reverse Recovery Loss
- Low Forward Voltage
- High Surge Current Capability
- Low Inductance Package



APPLICATIONS

- Inversion Welder
- Uninterruptible Power Supply (UPS)
- Plating Power Supply
- Ultrasonic Cleaner and Welder
- Converter & Chopper
- Power Factor Correction (PFC) Circuit



ABSOLUTE MAXIMUM RATINGS

T_c=25°C unless otherwise specified

Symbol	Parameter	Test Conditions	Values	Unit
V _R	Maximum D.C. Reverse Voltage		100	V
V _{RRM}	Maximum Repetitive Reverse Voltage		100	V
I _{F(AV)}	Average Forward Current	T _c =100°C , Per Diode	200	A
		T _c =100°C , Per Moudle	400	A
		T _c =100°C , 20KHz, Per Moudle	280	A
I _{F(RMS)}	RMS Forward Current	T _c =100°C , Per Diode	280	A
I _{FSM}	Non-Repetitive Surge Forward Current	1/2 Cycle , 60Hz, Sine	4000	A
I ² t	I ² t (For Fusing)	T _J =45°C , t=8.3ms, 60Hz, Sine	11200	A ² s
P _D	Power Dissipation		510	W
T _J	Junction Temperature		-40 to +150	°C
T _{STG}	Storage Temperature Range		-40 to +125	°C
Torque	Module-to-Sink	Recommended (M6)	3~4.7	Nm
Torque	Module Electrodes	Recommended (M6)	3~4.7	Nm
R _{θJC}	Thermal Resistance	Junction-to-Case	0.25	°C /W
Weight			92	g

ELECTRICAL CHARACTERISTICS

$T_c = 25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{RM}	Reverse Leakage Current	$V_R = 100\text{V}$	--	--	0.5	mA
		$V_R = 100\text{V}, T_J = 125^\circ\text{C}$	--	--	10	mA
V_F	Forward Voltage	$I_F = 200\text{A}$	--	0.65	--	V
		$I_F = 200\text{A}, T_J = 125^\circ\text{C}$	--	0.55	--	V

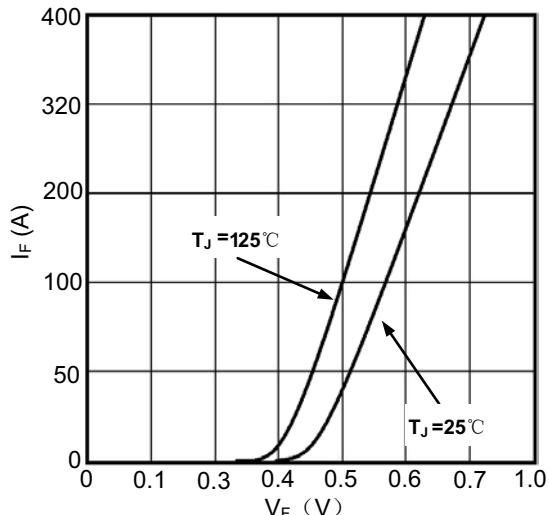


Figure 1. Forward Voltage Drop vs Forward Current

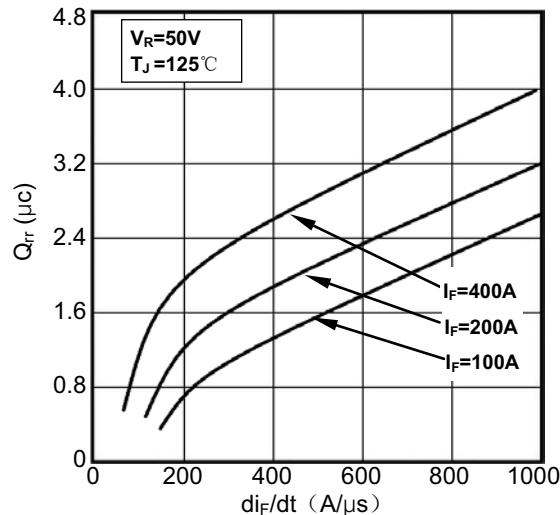


Figure 2. Reverse Recovery Charge vs di_F/dt

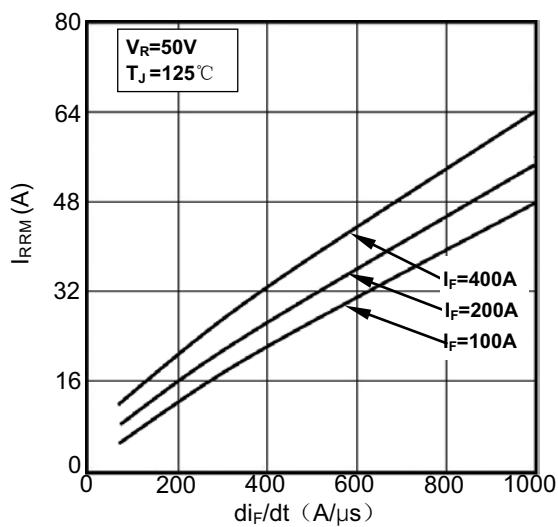


Figure 3. Reverse Recovery Current vs di_F/dt

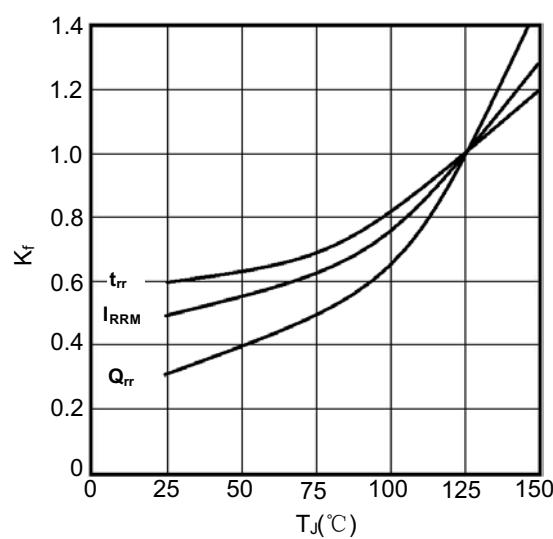


Figure 4. Dynamic Parameters vs Junction Temperature

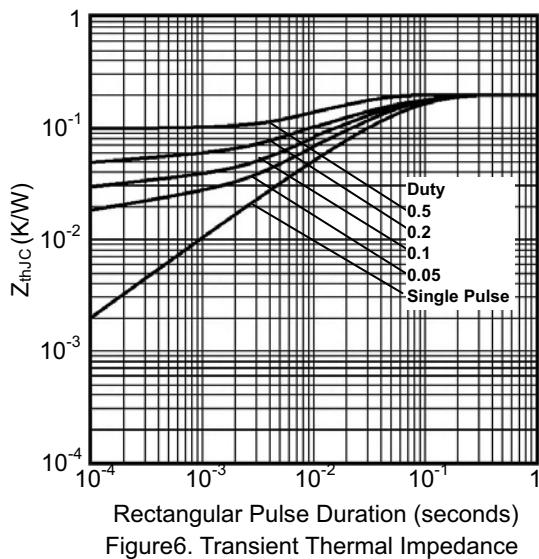
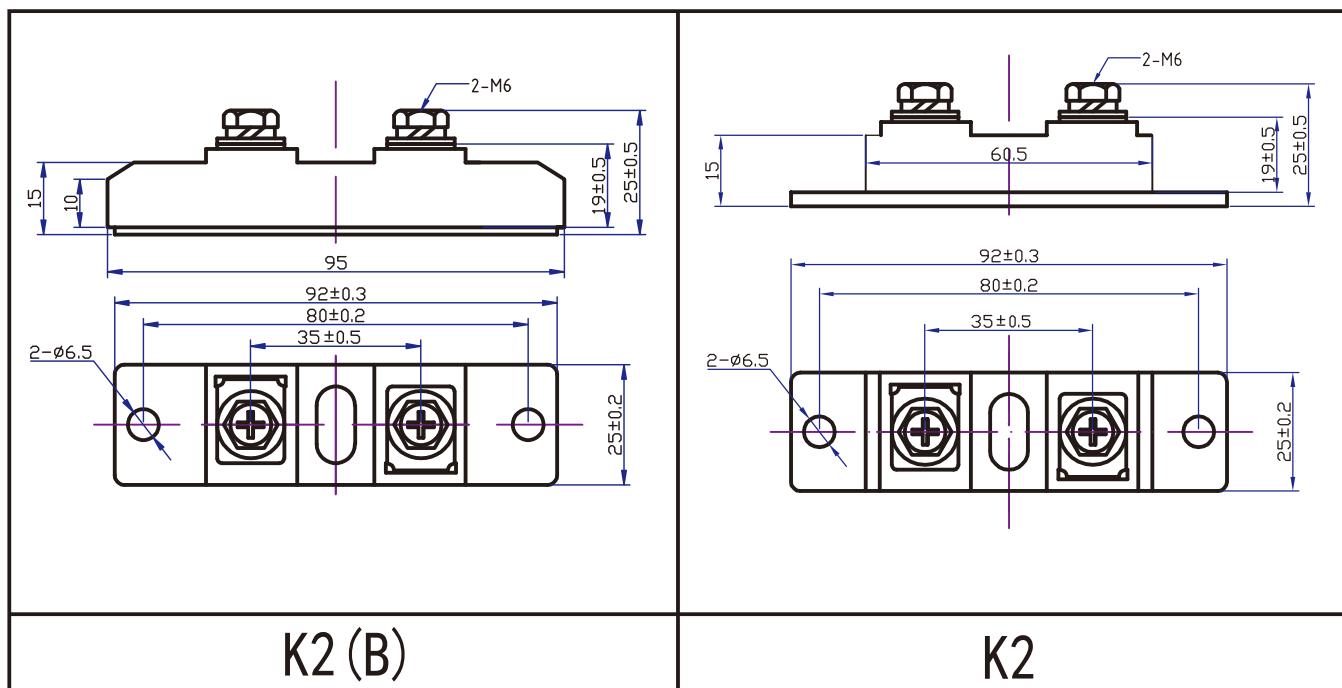


Figure 6. Transient Thermal Impedance

Package Outline



Dimensions (mm)